



US00RE37982E

(19) **United States**
(12) **Reissued Patent**
Yu

(10) **Patent Number:** **US RE37,982 E**
(45) **Date of Reissued Patent:** **Feb. 11, 2003**

(54) **METHOD FOR PREVENTING
ELECTROSTATIC DISCHARGE FAILURE IN
AN INTEGRATED CIRCUIT PACKAGE**

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(21) **Appl. No.:** **09/498,126**

(22) **Filed:** **Feb. 2, 2000**

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Reissue of:

(64) **Patent No.:** **5,715,127**
Issued: **Feb. 3, 1998**
Appl. No.: **08/642,194**
Filed: **May 6, 1996**

(51) **Int. Cl.⁷** **H02H 3/22**
(52) **U.S. Cl.** **361/56; 361/111; 361/220**
(58) **Field of Search** **361/56, 91.1, 111,
361/212, 91.5, 91.8, 220; 257/355, 357,
360, 361, 491, 546, 786**

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(57) ABSTRACT

An integrated circuit package includes a semiconductor chip, bonding pads on the semiconductor chip, a metal lead frame containing electrically with the semiconductor chip, a plurality of wired pins wire-bonded respectively to the bonding pads, and at least one non-wired pin. The non-wired pin is wire-bonded to the metal lead frame to prevent electrostatic discharge failure of the integrated circuit package due to electrostatic discharge stressing of the non-wired pin.

31 Claims, 4 Drawing Sheets

